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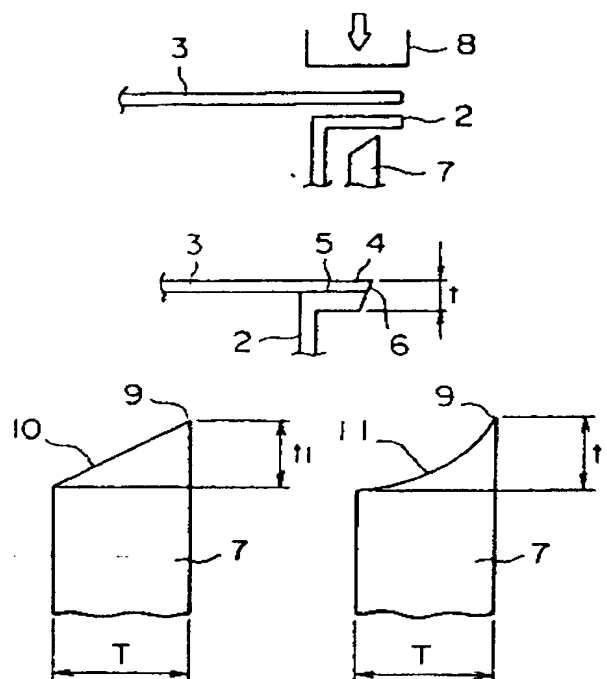
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TITLE : MANUFACTURING METHOD OF
BLISTER PACK



ABSTRACT : **PURPOSE:** To allow smooth opening of a blister pack which has a beautiful appearance and is excellent in sealing property, by a method wherein a ultrasonic wave receiving stand is provided with a tapered or curved shape blade and the thickness and height of the ultrasonic wave receiving stand are set at particular values proportional to the thickness at the joint of surface and rear materials.

CONSTITUTION: A blade of a receptacle stand of an ultrasonic phone 8 has a tapered shape, for example, tapered toward the tip at an angle of 10 - 60°, or tapered toward the tip at an angle of 10 - 30°, raised gradually, and curved toward the tip. The proportion (T/t) of the thickness T of the receiving stand to the total thickness t of the bound part of a surface material 2 and a rear material 3 is 0.5 - 10. The height t_1 of the blade is in a relationship of $t > t_1$. The surface material 2 made of transparent plastic and the rear material 3 are welded together at a joining area 4. The blister pack main body (surface material 2) and the rear material 3 as a cover are simultaneously supplied onto the blade shaped receiving stand. Then, the high-frequency phone 8 is pressed on the receiving stand 7 with ultrasonic waves radiated, and welding and cutting are performed at the same time.

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